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WHAT IS CLAIMED IS:

1. A heat conductivity and brightness enhancing structure for light-emitting diode, comprising a bracket having a cathode leg support, a bowl being formed on upper end of the cathode leg support for resting a light-emitting chip therein, said heat conductivity and brightness enhancing structure being characterized in that at least one depression is formed on a bottommost section of the bowl for receiving an adhesive therein, the depression having an opening directed to the chip, the opening having a diameter or area smaller than a bottom face of the chip, whereby during processing procedure, the adhesive is filled into the depression for preliminarily adhering the chip.
2. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein a column hole is formed through the cathode leg support from at least one depression of the bowl to outer side of the bracket.
3. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein a column blind hole is formed in the cathode leg support from a portion below at least one depression of the bowl by a certain thickness to outer side of the leg support.
4. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein the bowl is

formed of at least one stage of recessed face.

5. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the bowl is formed of at least one stage of recessed face.
6. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 3, wherein the bowl is formed of at least one stage of recessed face.
7. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein the circumference of the depression of the bowl is formed with concentric recesses.
8. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the circumference of the depression of the bowl is formed with concentric recesses.
9. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 3, wherein the circumference of the depression of the bowl is formed with concentric recesses.
10. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein the

circumference of the depression of the bowl is formed with concentric recesses.

11. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.
12. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.
13. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 3, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.
14. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.
15. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 7, wherein at least one of the cathode leg support and anode leg support of the bracket is formed with heat-radiating wings.

16. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.
17. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.
18. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 3, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.
19. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.
20. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 7, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.
21. The heat conductivity and brightness enhancing structure for

- light-emitting diode as claimed in claim 11, wherein the bottom face of the bracket is entirely attached to a conductive metal film of a PC board.
22. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.
23. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 2; wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.
24. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 3, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.
25. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.
26. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 7, wherein the bottom face of the bracket is partially attached to a conductive metal

film of a PC board.

27. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 11, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.
28. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 16, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board.
29. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 22, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board and partially suspended.
30. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 23, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board and partially suspended.
31. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 24, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board and partially suspended.

32. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 22, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.
33. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 23, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.
34. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 24, wherein the bottom face of the bracket is partially attached to a conductive metal film of a PC board, partially suspended and partially formed with columns which have column holes and are passed through the PC board.
35. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 1, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.
36. The heat conductivity and brightness enhancing structure for

light-emitting diode as claimed in claim 2, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

37. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 3, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

38. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 4, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

39. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 7, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

40. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 11, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.

41. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 16, wherein at least two fixing posts are disposed under the bottom face of the bracket

for insertion in the PC board.

42. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 22, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.
43. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 29, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.
44. The heat conductivity and brightness enhancing structure for light-emitting diode as claimed in claim 32, wherein at least two fixing posts are disposed under the bottom face of the bracket for insertion in the PC board.